

ABSTRACT

There is provided a semiconductor process equipment, including a process chamber (100), a first connector (210), a second connector (220), and a connecting device (300), the first connector (210) is connected to the process chamber (100), the connecting device (300) includes a first clamping member (330), a second clamping member (340), and a connecting assembly (350), the first clamping member (330) is sleeved on the first connector (210), the second clamping member (340) is sleeved on the second connector (220), one of the first clamping member (330) and the second clamping member (340) is provided with a positioning column (331), the other of the first clamping member (330) and the second clamping member (340) is provided with a positioning hole (341), the positioning column (331) is in positioning fit with the positioning hole (341) to make a central axis of the first connector (210) coincide with a central axis of the second connector (220), a gap is provided between the first connector (210) and the second connector (220), and one end of the positioning column (331) penetrates through the positioning hole (341) to be connected to the connecting assembly (350) to enable clamping of the first connector (210) and the second connector (220). The present disclosure can solve a problem that contact can be easily caused in a mating process of a gas pipeline of an existing semiconductor process equipment.

Fig. 3